

Zener Diode DZ2W04300L

DZ2W04300L Silicon epitaxial planar type

For constant voltage / For surge absorption circuit DZ24043 in Mini2 type package

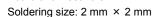
Features

- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: 9J

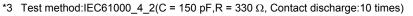
Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25	°C		
Parameter	Symbol	Rating	Unit
Repetitive peak forward current	IFRM	500	mA
Forward current	IF	200	mA
Total power dissipation ^{*1}	PT	1	W
Non-repetitive reverse power surge *2	PZSM	100	W
Electrostatic discharge *3	ESD	±30	kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	С°
Storage temperature	Tstg	-55 to +150	С°
Note: *1 Mounted on ceramics print circuit bo	ard.		
Board size: 50 mm × 50 mm			
Board thickness: 0.8 mm			



*2 t = 0.1ms



■ Electrical Characteristics Ta = 25 °C ± 3 °C

					1	
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 200 mA			1.2	V
Zener voltage *1, *2	VZ	IZ = 20 mA	4.09	4.30	4.52	V
Zener operating resistance	RZ	IZ = 20 mA			80	Ω
Reverse current	IR	VR = 1 V			50	μA
Temperature coefficient of zener voltage *3	SZ	IZ = 20 mA		-1.4		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

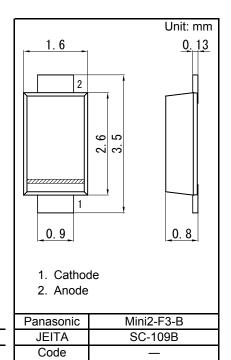
2. Absolute frequency of input and output is 5 MHz.

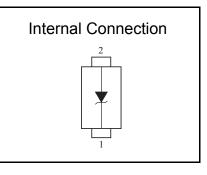
3. *1 The temperature must be controlled 25°C for VZ mesurement.

VZ value measured at other temperature must be adjusted to VZ (25°C)

*2 VZ guaranted 20 ms after current flow.

*3 Tj = 25°C to 150°C

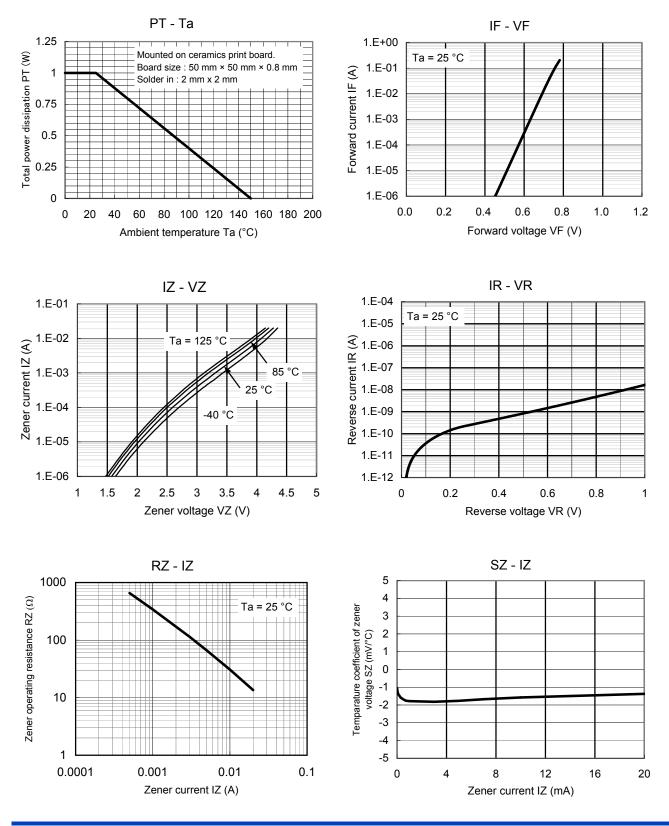






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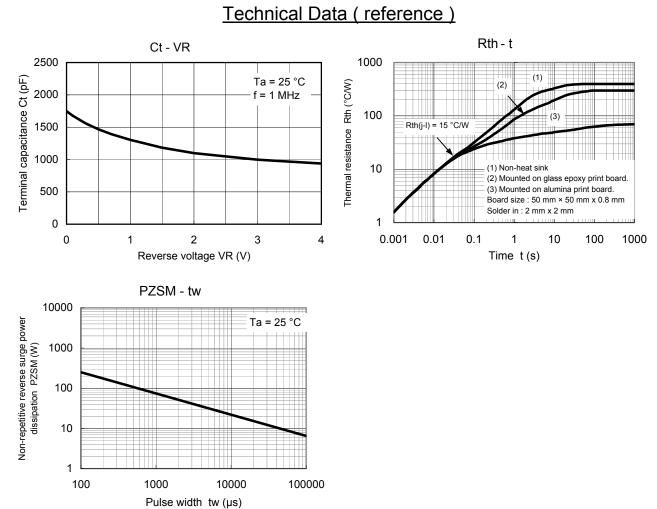
Technical Data (reference)

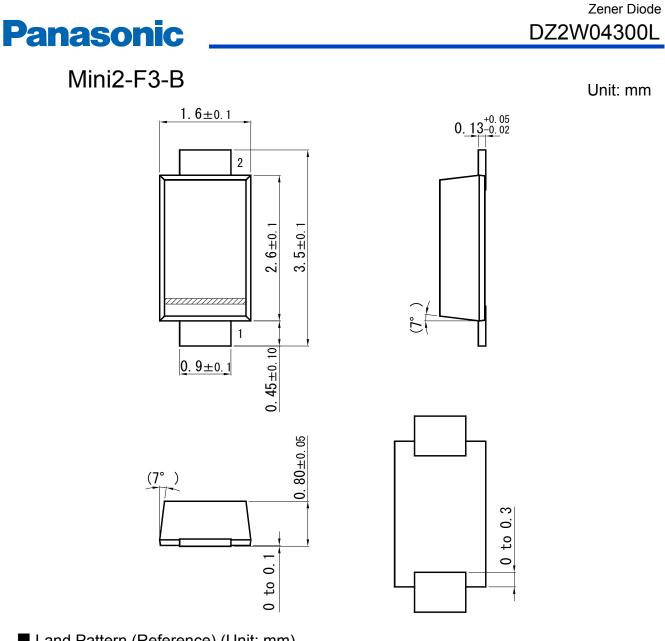


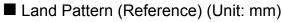
Established : 2011-03-11 Revised : 2013-05-08

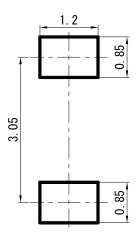


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